

Description

The ACE7400 is the N-Channel logic enhancement mode power field effect transistors are produced using high cell density, DMOS trench technology.

This high density process is especially tailored to minimize on-state resistance.

These devices are particularly suited for low voltage application such as cellular phone and notebook computer power management and other batter powered circuits, and low in-line power loss are needed in a very small outline surface mount package.

Features

- 30V/2.8A, $R_{DS(ON)}=77m\Omega @V_{GS}=10V$
- 30V/2.3A, $R_{DS(ON)}=85m\Omega @V_{GS}=4.5V$
- 30V/1.5A, $R_{DS(ON)}=110m\Omega @V_{GS}=2.5V$
- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability

Application

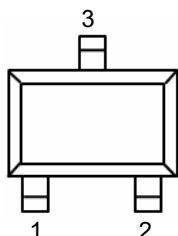
- Power Management in Note book
- Portable Equipment
- Battery Powered System
- DC/DC Converter
- Load Switch
- DSC
- LCD Display inverter

Absolute Maximum Ratings

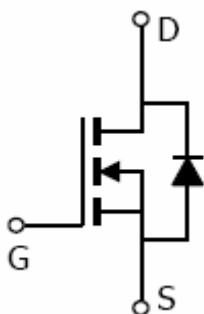
Parameter	Symbol	Max	Unit
Drain-Source Voltage	V_{DSS}	30	V
Gate-Source Voltage	V_{GSS}	± 12	V
Continuous Drain Current ($T_J=150^\circ C$)	I_D	$T_A=25^\circ C$	2.8
		$T_A=70^\circ C$	2.1
Pulsed Drain Current	I_{DM}	10	A
Continuous Source Current (Diode Conduction)	I_S	1.25	A
Power Dissipation	P_D	$T_A=25^\circ C$	0.33
		$T_A=70^\circ C$	0.21
Operating Junction Temperature	T_J	150	$^\circ C$
Storage Temperature Range	T_{STG}	-55/150	$^\circ C$
Thermal Resistance-Junction to Ambient	$R_{\theta JA}$	100	$^\circ C/W$

Packaging Type

SOT-23-3



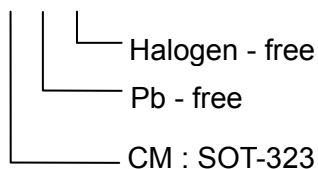
Pin	Symbol	Description
1	G	Gate
2	S	Source
3	D	Drain



Ordering information

Selection Guide

ACE7400 XX + H



Electrical Characteristics

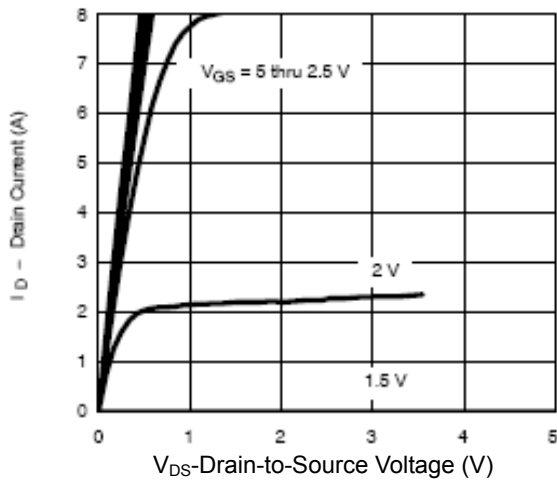
T_A=25°C, unless otherwise noted

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =-250uA	30			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =-250uA	0.8		1.6	
Gate Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±12V			±100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =24V, V _{GS} =0V			-1	uA
		V _{DS} =24V, V _{GS} =0V T _J =55°C			10	
On-State Drain Current	I _{D(ON)}	V _{DS} ≥ 4.5V, V _{GS} =10V	6			A
		V _{DS} ≥ 4.5V, V _{GS} =-4.5V	4			
Drain-Source On-Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =2.8A		0.062	0.077	Ω
		V _{GS} =4.5V, I _D =2.3A		0.070	0.085	

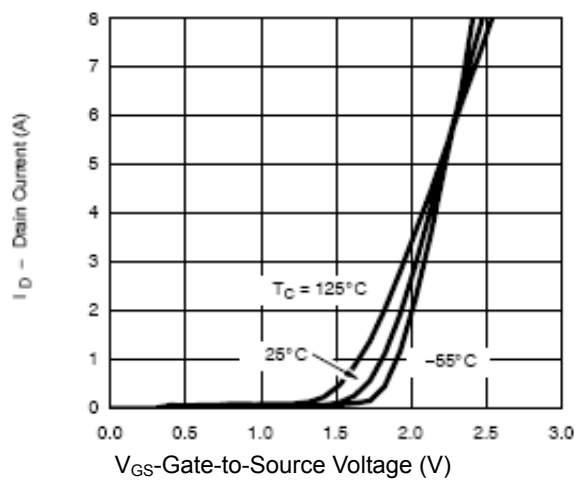
		$V_{GS}=2.5V, I_D=1.5A$	0.095	0.110	
Forward Transconductance	G_{fs}	$V_{DS}=4.5V, I_D=2.8A$	4.6		S
Diode Forward Voltage	V_{SD}	$I_S=1.25A, V_{GS}=0V$	0.82	1.2	V
Dynamic					
Total Gate Charge	Q_g	$V_{DS}=15V, V_{GS}=4.5V, I_D=-2.0A$	4.2	6	nC
Gate-Source Charge	Q_{gs}		0.6		
Gate-Drain Charge	Q_{gd}		1.5		
Input Capacitance	C_{iss}	$V_{DS}=15V, V_{GS}=0V, f=1MHz$	350		pF
Output Capacitance	C_{oss}		55		
Reverse Transfer Capacitance	C_{rss}		41		
Turn-On Time	$t_{d(on)}$	$V_{DD}=15V, R_L=10\Omega, V_{GEN}=10V, R_G=3\Omega$	2.5		nS
	t_r		2.5		
Turn-Off Time	$t_{d(off)}$		20		
	t_f		4		

Typical Performance Characteristics

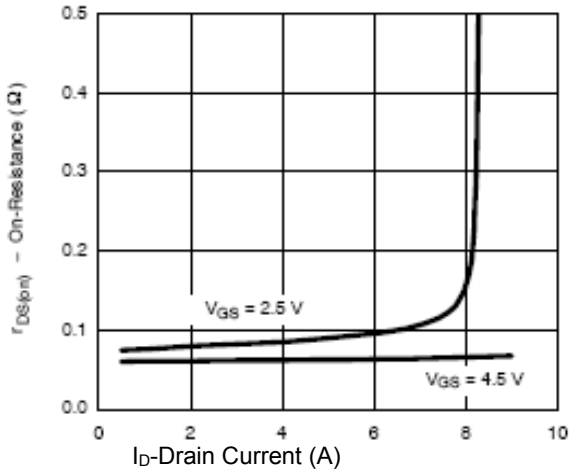
Output Characteristics



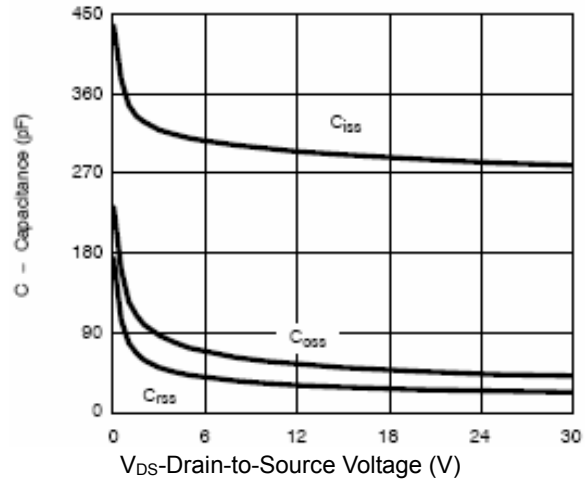
Transfer Characteristics



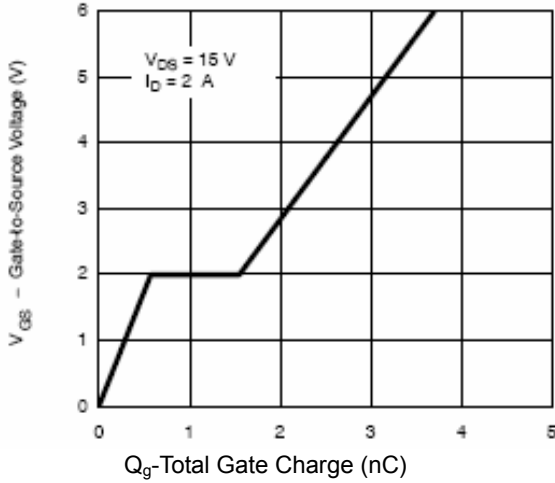
On-Resistance vs. Drain Current



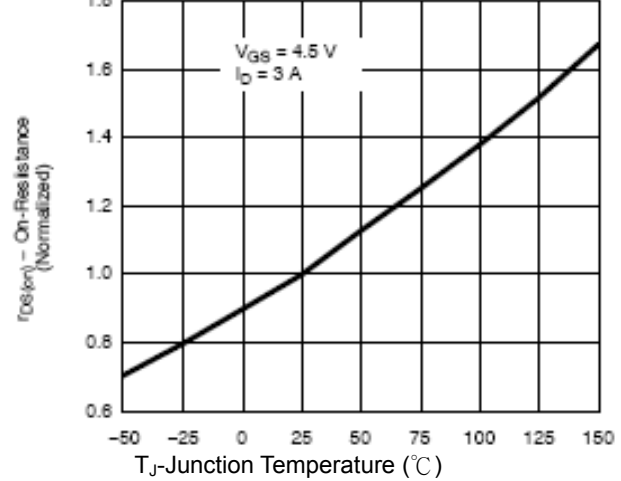
Capacitance



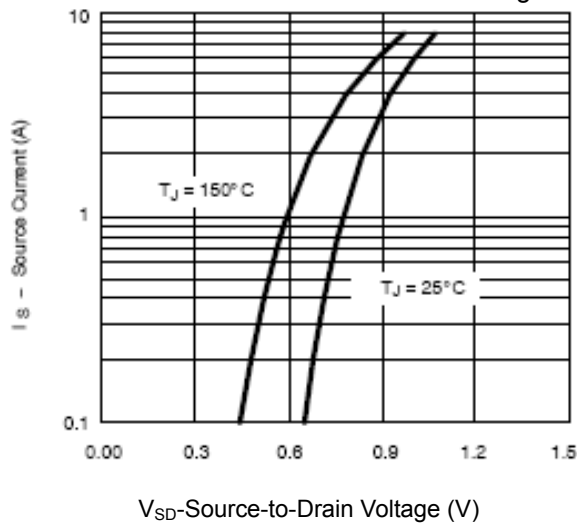
Gate Charge



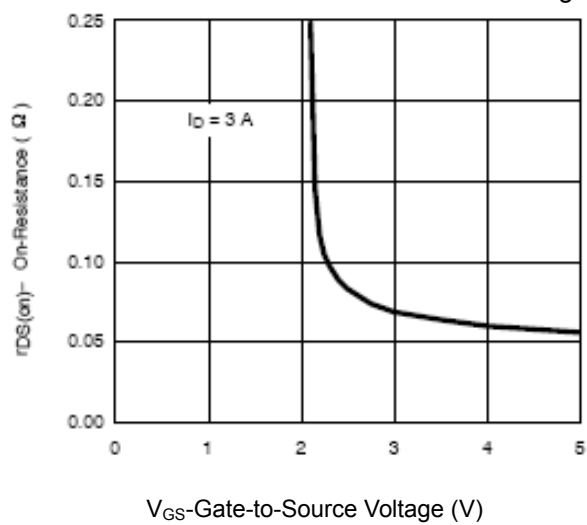
On-Resistance vs. Junction Temperature

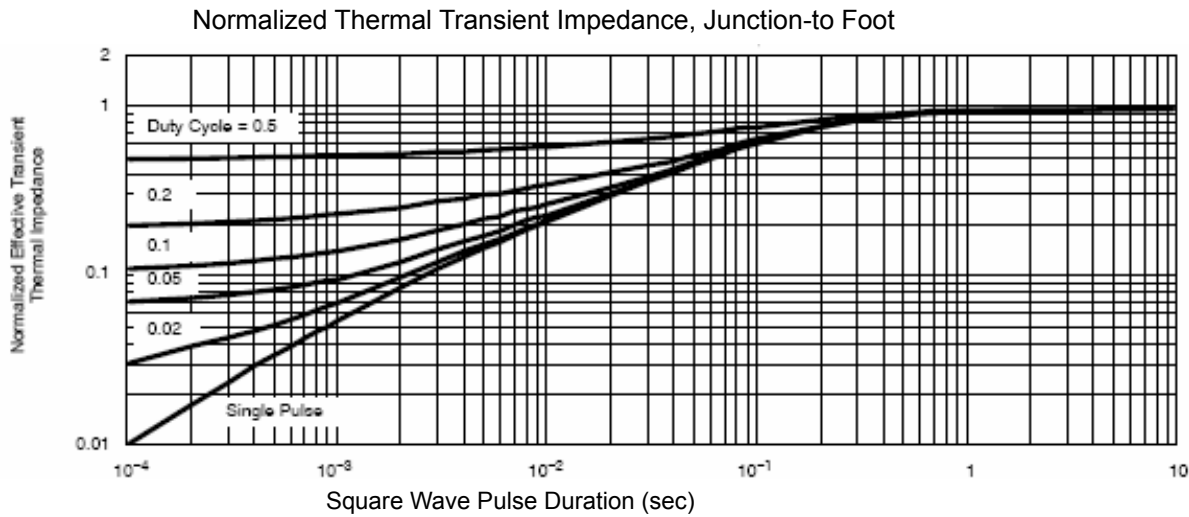
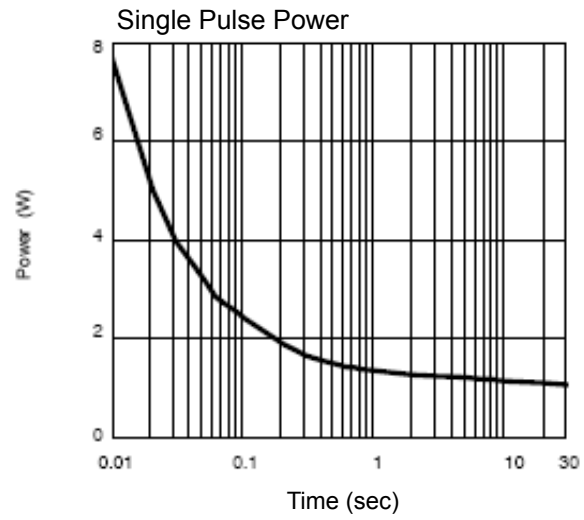
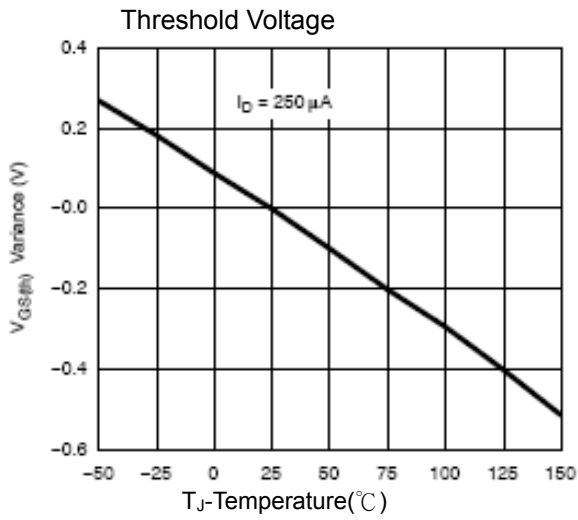


Source-Drain Diode Forward Voltage



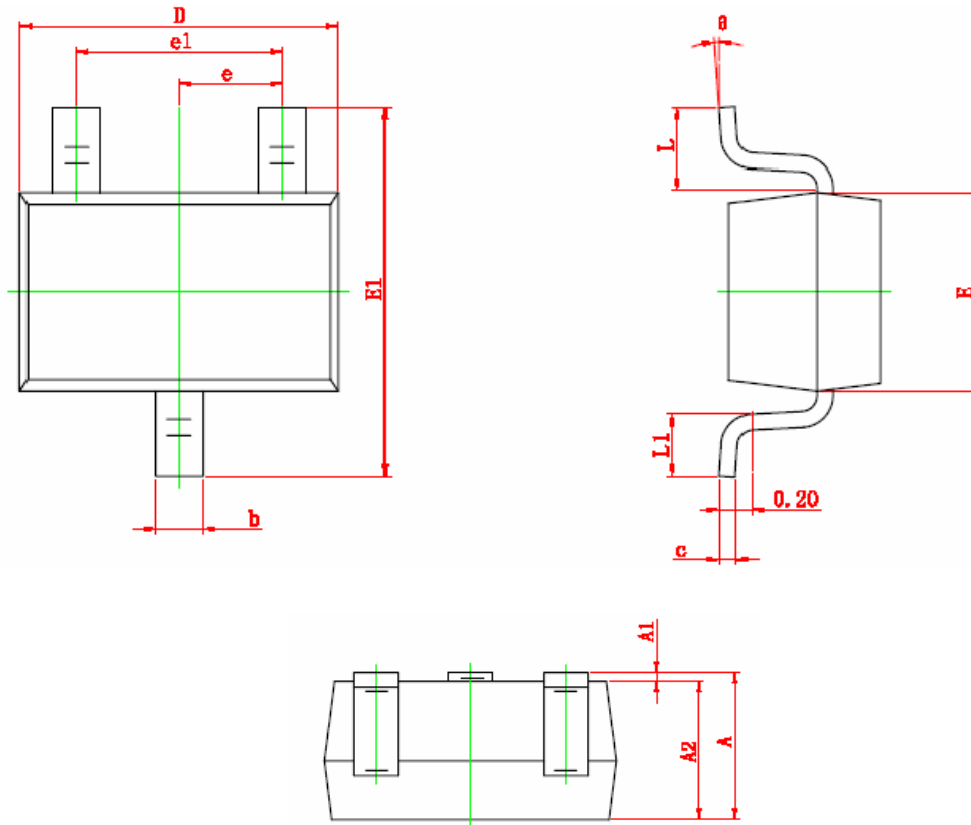
On-Resistance vs. Gate-to-Source Voltage





Packing Information

SOT-323



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.200	0.400	0.008	0.016
c	0.080	0.150	0.003	0.006
D	2.000	2.200	0.079	0.087
E	1.150	1.350	0.045	0.053
E1	2.150	2.450	0.085	0.096
e	0.650 TYP		0.026 TYP	
e1	1.200	1.400	0.047	0.055
L	0.525 REF		0.021 REF	
L1	0.260	0.460	0.010	0.018
θ	0°	8°	0°	8°

Notes

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1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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